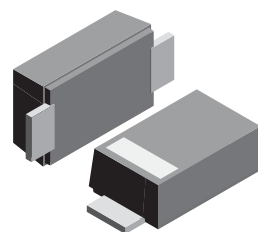


VOLTAGE RANGE: 20 - 100V

CURRENT: 2.0 A

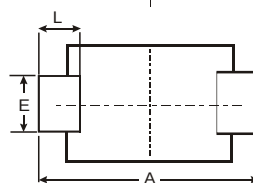
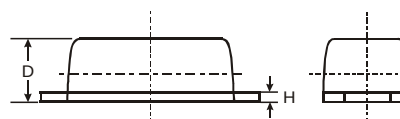
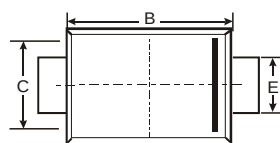


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O

Mechanical Data

- Case:SMBF , Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.0018 ounces,0.05grams



SMBF			
Dim	Min	Max	Typ
A	5.45	5.55	5.50
B	4.27	4.33	4.30
C	3.57	3.63	3.60
D	1.32	1.38	1.35
E	1.96	2.00	1.98
H	0.019	0.021	0.20
L	0.73	0.77	0.75
All Dimensions in mm			



Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SK22F	SK23F	SK24F	SK25F	SK26F	SK28F	SK210F	Unit
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	V
Maximum average forward rectified current at T _L (see fig.1)	I _(AV)	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50.0							A
Maximum instantaneous forward voltage at 2.0A	V _F	0.55			0.70		0.85		V
Maximum DC reverse current T _A =25°C at rated DC blocking voltage T _A =100°C	I _R	0.5							mA
		20			10				
Typical junction capacitance (NOTE 1)	C _J	220			180				pF
Typical thermal resistance (NOTE 2)	R _{θJA}	75.0							°C/W
Operating junction temperature range	T _J	-65 to +125			-65 to +150				°C
Storage temperature range	T _{STG}	-65 to +150							°C

Note:1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

RATINGS AND CHARACTERISTIC CURVES SK22F THRU SK210F

